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ICS 31.200
CCS L56

SJ

INDUSTRY STANDARD OF THE PEOPLE'S REPUBLIC OF CHINA

SJ 21496-2018

Technical requirements for gold plating process of microelectronic packaging shell

微电子封装外壳 镀金工艺技术要求

(English Translation)

Implemented on: March 1, 2019

Issued by: Ministry of Industry and Information Technology

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https://chinastandards.org/standards/sj-21496-2018

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1 Foreword

SJ 21496-2018 is issued by Ministry of Industry and Information Technology.

The SJ prefix, without a suffix, marks a mandatory standard: within its scope, compliance is required.

The document runs to 8 pages in English translation.

2 Scope Preview

SJ 21496-2018 falls under ICS 31.200, in the field of electronics.

This catalogue holds 133 other SJ standards in that field.

In this catalogue, SJ standards carry edition years from 1965 to 2021.

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3 About this standard

Sector: Electronics Industry Standard

Issued by: Ministry of Industry and Information Technology

English translation: about 8 pages (approximate)

Chinese original: about 12,177 characters

4 Related standards

Standards on related subjects:

SJ/T 11890-2023 - Design requirement of energy conservation for LED displays

SJ/T 11891-2023 - Energy efficiency measurement method for LED displays

GB/T 35010.6-2018 - Semiconductor die products -- Part 6: Requirements for concerning thermal simulation

SJ 21634-2021 - Semiconductor integrated circuits - Multi-node low-voltage differential signaling (M-LVDS) test methods

SJ 21619-2021 - DC input passive EMI filter test method

SJ 21495-2018 - Microelectronic packaging shell packaging technology requirements

5 Classification and status

International classification (ICS): 31.200

Chinese Standard Classification (CCS): L 56

Prefix SJ: mandatory standard.

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